# **Investor Relations**

TOKAI CARBON KOREA

# **Disclaimer**

All information regarding management performance and financial results of Tokai Carbon Korea (the "Company") during the end of 2018 as contained herein has been prepared in accordance with International Financial Reporting Standards ("IFRS").

The information regarding results of 2018 has been prepared in advance, prior to being reviewed by outside auditors, solely for the convenience of investors of the Company, and is subject to change in the process of final reviewing by external auditors.

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# I . About TCK

**Company Overview** 

**Product Introduction** 

**Business Performance** 

**Stock Information** 



# **Company Overview**

#### Higher Tech Node Solution Provider

Established	Aug. 1996 (23 years)
CEO	Yeong-soon Park
Location	Ansung City, Gyeonggi-do, Republic of Korea
Capital	5.8 Billion KRW
Employees	335 (As of Dec. 2018)
Main Products	CVD SiC components, High-purity Graphite components, Wafer Susceptors, etc.
Home page	http://www.tck.co.kr





#### **Major Award Career**

2015.12 Technology Grand Prize of the Prime Minister

2016.02 Best Partner Award (Samsung)

2016.03 Exemplary Taxpayer Award of Premier

2016.11 Supplier Aftermarket Collaboration Award (Applied Materials)

**2017.10** Supplier Excellence Award (Lam Research)

2017.11 Accelerated Growth and Performance Award (Applied Materials)

2018.02 Best Contribution Award (Samsung)

# **Product Introduction**

#### **High-purity Graphite Components**

#### **Application**

- -. Crystal Puller components for producing semiconductor / Solar Cell silicon wafer.
- -. High-purity graphite Hot Zone parts for CZ Process
  - → Heater / Crucible / Shield / Reflector...

#### M/S

- -. More than 60% in Domestic Market
- -. Revenue Portion: 15%



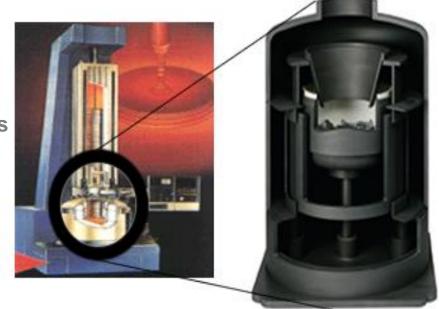












# **Product Introduction**

# **Wafer Susceptors**

#### **Application**

- -. Chamber parts that hold the wafers
- -. MOCVD for LED
- -. ALD for Semiconductor
- -. Epi for Semiconductor



#### M/S

- -. 100% of Aixtron's equipment in Domestic Market
- -. Revenue Portion: 7%

# SiC Pyro TaC

#### **Customers**











# **Product Introduction**

#### **CVD SiC components**

#### **Application**

- -. Critical Chamber Parts, for Dry Etcher, holding the Wafer and Focusing Plasma
- -. CVD SiC Ring for Dry Etcher
- -. CVD SiC Dummy Wafer for Diffusion furnace
- -. Plasma Shower Head for Dry Etcher

#### M/S

- -. More than 80% in Worldwide Market
- -. Revenue Portion: 78%

#### **Customers**



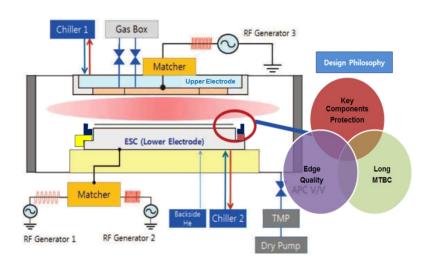








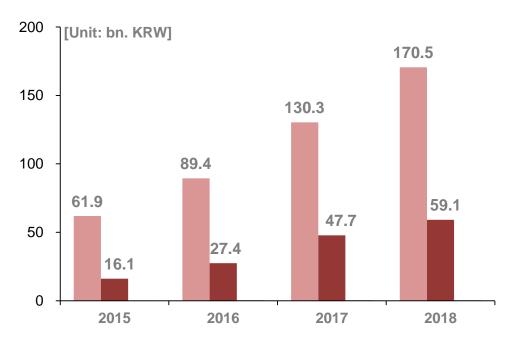






# **Business Performance**

## CAGR(2015~2018): 40.2%



Category	2015	2016	2017	2018
Revenue	61.9	89.4	130.3	170.5
OP	16.1	27.4	47.7	59.1
OP Margin	26.0%	30.7%	36.6%	34.7%
CAPEX	11.6	25.2	11.3	12.2
Asset	103.4	131.5	168.8	214.1
Debt Ratio	9.9%	15.4%	16.0%	16.3%

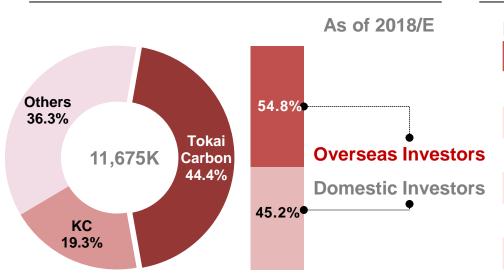
[Unit: bn. KRW]

- Global No.1 Production capacity for CVD SiC
- Dominant M/S in major product lines
- Stable financial structure and sustainable high margin
- High-Distribution policies
- Customer satisfaction with superior Q/C/D
- Business diversification with continuous R&D

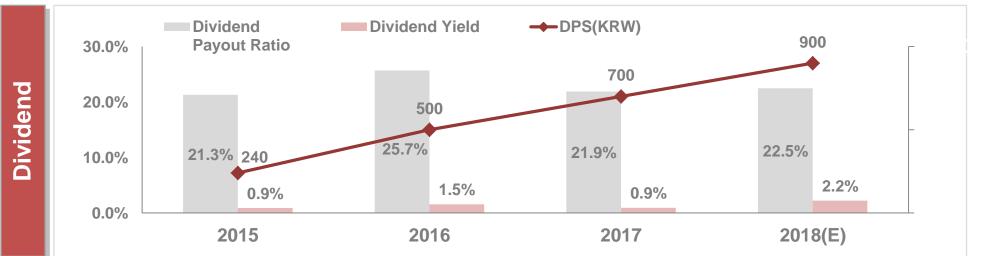
# **Stock Information**

#### **Status of Shareholders**

#### **Investment Information**



[Unit: bn. KRW]		The End of Year		
Category	2016	2017	2018	
ROIC	23.3%	30.5%	29.9%	
ROE	21.9%	28.8%	28.4%	
PER	16.6	24.1	10.1	
PBR	3.3	6.2	2.6	
EPS(KRW)	1,948	3,195	4,005	
Market Value	377.7	899.0	471.7	



\*Distribution in 2018 is a forecast that takes into account historical dividend tendencies and may vary according to the results of accounting audit and meeting of Shareholders.

# II. TCK's Future

**Market Forecast** 

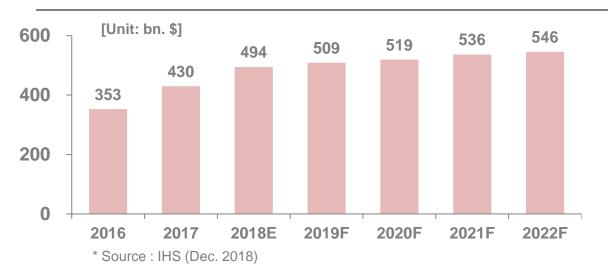
**New Green-Field Construction** 

**New Business Development** 



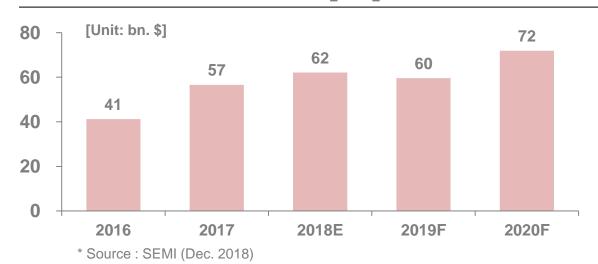
# **Market Forecast**

#### **Semiconductor Revenue Forecast**



- -. IoT and Industry 4.0 driving an explosion of data
- -. More data needs to be processed and stored than ever before

## **Semiconductor Equipment Revenue Forecast**



- -. Short-term Decline in 2019
- -. However, CAGR(18~20) 7.6%

# **New Green-Field Construction**

Investment Approval for New Plant 48.3bn, KRW

2018.07

**Building Construction** 

**CVD Reactors Installation** 

**Equipment Set-up** 

**In Progress** 

Starting up

2019.09



#### **Total Plant Overview**

-. Land Space : 26,856 m<sup>2</sup>

-. Building Space: 25,589 m<sup>2</sup>

-. Production Items

· CVD SiC components

Wafer Susceptor

High purity Graphite components

# **New Business Development**

#### Continuous Development of New Products for Sustainable Growth

## **Platform Technology Development**

#### **CVD TaC**

- -. For Wafer Susceptors Applicable to high-temp. process over 1,500 ℃
- -. SiC Epitaxial Growth
- -. UV-LED
- -. Single Crystal SiC Growth

#### **Single Crystal SiC**

- -. Substrate materials for Power Device
- -. Development with High Temperature CVD
- -. Faster growth rate
- -. Easier Defect Control







# **New Business Development**

#### Continuous Development of New Products for Sustainable Growth

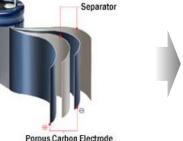
#### **Key Material for Battery Industry**



#### **Electrode Material for Super Capacitor**









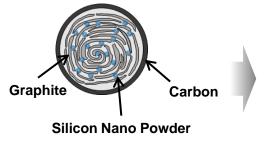
**Activated Carbon** 

Supercap. Cell

Supercap. Module

# Silicon – Graphite Anode

#### Si-Graphite Composite type Anode material for LiB









LiB Cell

LiB Module

# III. Appendix

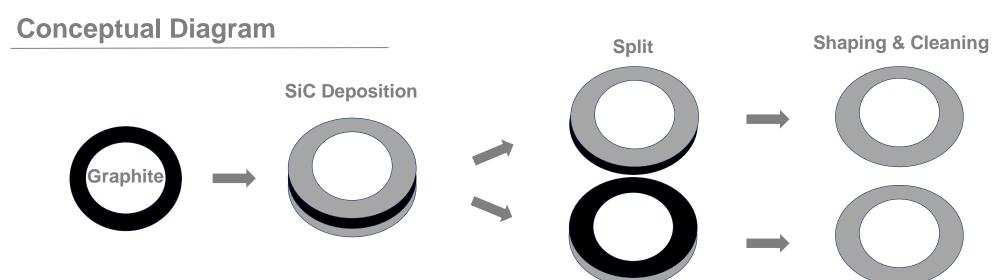
**CVD SiC Ring Mfg. Process Schematics for Dry Etcher** 



# **CVD SiC Ring Mfg. Process**

#### **Production Process**

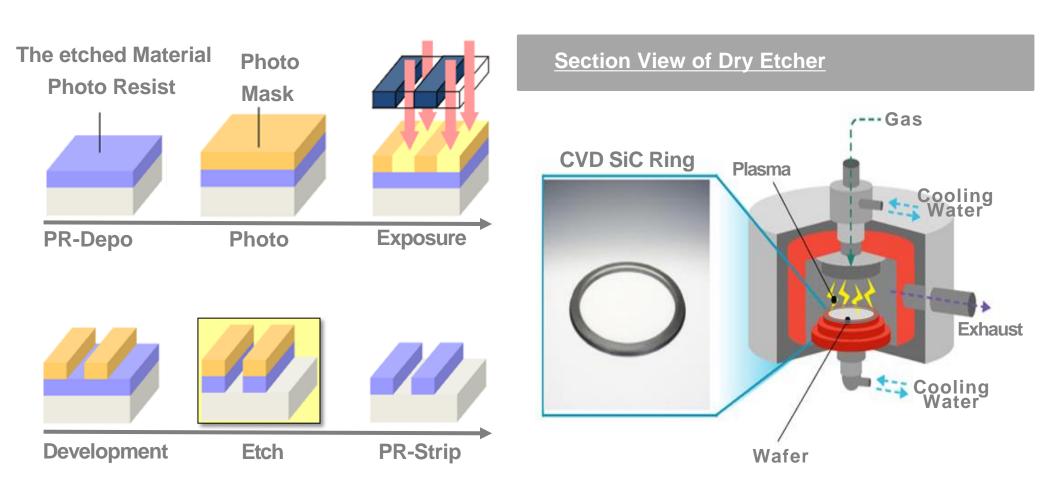




# **Schematics for Dry Etcher**

#### **Etching Process & CVD SiC Ring**

Process to shape a thin film into a designed pattern on semiconductor



# Forerunner of Functional Materials & Components

# Thank You

